

ABSTRACT OF THE DISCLOSURE

METHOD FOR THE REMOVAL OF SURFACE OXIDES BY ELECTRON ATTACHMENT

Described herein are a method and an apparatus for removing metal oxides and/or forming solder joints on at least a portion of a substrate surface within a target area. In one particular embodiment, the method and apparatus to reduce metal oxides and form a solder joint within a substrate comprising a layer having a plurality of solder bumps by providing one or more energizing electrodes and exposing at least a portion of the layer and solder bumps to the energizing electrode.

Fig. 20b